

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IFX1051LE	**Issued**	24. June 2021
MA#	MA005432737		
Package	PG-TSON-8-1	**Weight***	27.04 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.493	5.52	5.52	55194	55194
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		109	
	non noble metal	zinc	7440-66-6	0.012	0.04		436	
	non noble metal	iron	7439-89-6	0.236	0.87		8730	
	non noble metal	copper	7440-50-8	9.586	35.45	36.37	354472	363747
wire	non noble metal	copper	7440-50-8	0.035	0.13	0.13	1306	1306
encapsulation	organic material	carbon black	1333-86-4	0.029	0.11		1082	
	plastics	epoxy resin	-	1.507	5.57		55714	
	inorganic material	silicondioxide	60676-86-0	13.092	48.42	54.10	484118	540914
leadfinish	non noble metal	tin	7440-31-5	0.382	1.41	1.41	14133	14133
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1607	1607
glue	plastics	epoxy resin	-	0.156	0.58		5775	
	noble metal	silver	7440-22-4	0.468	1.73	2.31	17324	23099
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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